ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoc nternational and Pan-Ameri	kburn, Illinois	. All rights reserv	tion with lower	level p	parts, the	declaration	n encomp		er level mate	erials for	which th	item is an assembly e manufacturer has eclaration.	
1752-2 1.1	•	Web Site for Informat //www.ipc.org/IPC-1		Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/No, Homogeneous Materials and						and Mfg Informat					
Supplier Information															
Company Name *		Company Unique ID		Unique ID Au	uthority	Resp	onse Date	e *	Re	sponse Doc	ument ID				
Mindspeed Techologies	Inc	N/A		N/A			03-22								
Contact Name * Title - Contact				Phone - Contact *			Email - Contact *								
Cynthia Ong Program Manager				949-579-5515			cynthia.ong@mindspeed.com								
Authorized Representati	Authorized Representative * Title - Representative			Phone - Representative *			Email - Representative *			Supplier Comments or URL for Additional Information					
Amy Teng	Amy Teng Quality Engineer			604-6328114	amy.t	amy.teng@mindspeed.com									
Requester Item Numbe	r	Mfr Item Number		Mfr Item Name)	Effectiv	ve Date	Version	Manufact	ıring Site	Weight *	UC	OM	Unit Type	
M21151G-14		M21151G-14		35FCBGA 1156		2010-	10-27	D	ASE, Tai	wan 19,242.22		e mg	7	EACH	
Alternate Recommenda	ation			NA			Alternate Item Co		Item Com						
Manufacturing Proces	ss In	formation													
Terminal Plating / Grid Array	Mater	al	Terminal Ba	ase Alloy	J-STD-020 MSL R	ating	Peak Prod	ess Body	Temperatu	re Max Time	at Peak Tem	perature	Number	of Reflow Cycles	
SAC 305 N/A			N/A	5			245 (C 40 sec			conds 3		
Comments															
N/A															

Save the fields in this form to a file Export Data Import fields from a file into this form		Locked
RoHS Material Composition Declaration	Declaration Type	* Simplified
RoHS Directive 2002/95/EC RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexaval 2002/95/EC Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Ca		rominated Biphenyls (PBB),
upplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is at Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws the upplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification ritten agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and or remedies provided as part of that agreement, will be the emedies for issues that arise regarding information the Supplier provides in this form.	nat implement the RoHS Direct applier has not independently von in this paragraph. If the Com	ive. Company acknowledges that erified information provided by others, npany and the Supplier enter into a
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions	Supplier Acceptance *	Accepted
exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then sel bove and choose all applicable exemptions.	lect the corresponding re	esponse in the RoHS Declaration
Exemption List Version EL-2006/690/EC		
15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.		
Declaration Signature		

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier	Digital	Signature
----------	---------	-----------

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

Item/SubItem		Homogeneous	Weight	Unit of	Level	Substance Category	Substance	CAS	Evenne	Weight	Unit of	Tolerance		PPM
Name		Material	weight	Measure	Levei	Substance Category	Substance	CAS	Exempt	weight	Measure	-	+	FFI
M21151G-14		Heatslug	5,395.96	mg	С	GROUP-C	Chrome	Trade Secret		2.69798	mg			500
					С	GROUP-C	Copper	7440-50-8		5,360.880	mg			993
					В	Nickel/Nickel Compou	Nickel	7440-02-0		32.37576	mg			1,6
		Ball mount flux	2	mg	С	GROUP-C	Nomionic surfactant	68439-49-6		0.56	mg			279
					С	GROUP-C	Bara Terpineol	8000-41-7		0.66	mg			329
					С	GROUP-C	Anime surfactant	61790-85-0		0.78	mg			389
		Thermally condu	75	mg	С	GROUP-C	Other	Trade Secret		18.375	mg			24
					С	GROUP-C	Inorganic Compounds	Trade Secret		33.75	mg			44
					С	GROUP-C	Polymer Resin	Trade Secret		20.625	mg			27
					С	GROUP-C	Allylether	Trade Secret		2.25	mg			29
		Substrate	8,850.33	mg	С	GROUP-C	Palladium	67762-90-7		3.75	mg			42
					С	GROUP-C	Thallium	Trade Secret		21.66	mg			2,
					С	GROUP-C	Phosphorous	26265-08-7		482.96	mg			54
							Calcium oxide	68-12-2		2.74	mg			14
					С	GROUP-C	Aluminum oxide	7440-31-5		3.22	mg			36
					С	GROUP-C	Zirconium oxide	Trade Secret		219.44	mg			24
					С	GROUP-C	Copper	Trade Secret		3.75	mg			42
					С	GROUP-C	Strontium oxide	64742-94-5		2.74	mg			30
					С	GROUP-C	Gold	Trade Secret		0.68	mg			76
							Barium oxide	108-94-1		13.71	mg			71
					С	GROUP-C	Chromium oxide	25068-38-6		53.15	mg			6,
					С	GROUP-C	Silicon dioxide	7440-50-8		1,199.02	mg			13
					С	GROUP-C	Copper oxide	Trade Secre		5	mg			56

			A	Lead/Lead Compound	Boron oxide	7439-92-1	1.89	mg	213.55
			С	GROUP-C	Nickel	65997-17-3	643.95	mg	72,759
Stiffener ring	3,178.73	3,178.73 mg		GROUP-C	Chrome	Trade Secret	1.589365	mg	500
	•		В	Nickel/Nickel Compou	Nickel	7440-02-0	19.07238	mg	991.17
			С	GROUP-C	Copper	7440-50-8	3,158.06	8mg	993,49
Die	386.83	mg	С	GROUP-C	Silicon	7440-21-3	386.83	mg	999,99
Flux	1	mg	С	GROUP-C	Distillates, petroleum, st	64741-44-2	0.175	mg	174,99
			С	GROUP-C	Diethanolamine	111-42-2	0.0505	mg	50,499
			С	GROUP-C	Modified rosin	65997-05-9	0.724	mg	723,99
			С	GROUP-C	Triethanolamine	102-71-6	0.0505	mg	50,499
тім	120	mg	С	GROUP-C	Zinc Oxide	1314-13-2	42	mg	349,99
	•		С	GROUP-C	Resin	Trade Secret	78	mg	649,99
Underfill	42	mg	С	GROUP-C	Bisphenol A type liquid	25068-38-6	1.26	mg	29,999
	•		С	GROUP-C	Additives	Trade Secret	0.84	mg	19,999
			С	GROUP-C	Silicon dioxide	60676-86-0	21	mg	499,99
			С	GROUP-C	Organic acid anhydride	Trade Secret	8.4	mg	199,99
			С	GROUP-C	Phenolic resin	9003-35-4	0.84	mg	19,999
			С	GROUP-C	1,6-Bis(2,3-epoxypropox	27610-48-6	8.4	mg	199,99
			С	GROUP-C	Carbon black	1333-86-4	0.42	mg	9,999.9
			С	GROUP-C	Amine type accelerator	Trade Secret	0.84	mg	19,999
lnk	0.5	mg	С	GROUP-C	Phenol	108-92-5	0.015	mg	29,999
		<u> </u>	С	GROUP-C	Carbon black	1333-86-4	0.3	mg	599,99
			С	GROUP-C	Formaldehyde	50-00-0	0.065	mg	129,99
			С	GROUP-C	Propylene glycol monor	108-65-6	0.04	mg	79,999
			С	GROUP-C	Isobutyl alcohol	78-83-1	0.015	mg	29,999
			С	GROUP-C	Triethyl phosphate trieth	78-40-0	0.065	mg	129,99
Solder Ball	1,017.78	mg	С	GROUP-C	Cu	7440-50-8	5.0889	mg	5,000
		ı I	С	GROUP-C	Sn	7440-31-5	971.9799	mg	954,99
			С	GROUP-C	Ag	7440-22-4	40.7112	mg	40,000
Bump	172.09	mg	С	GROUP-C	Sn	7440-31-5	6.5646	mg	38,146
			Α	Lead/Lead Compound	Pb	7439-92-1	165.5254	mg	961,85